

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	[HEAT SINK FOR CHIP PACKAGE AND BONDING METHOD THEREOF]							
Application Number :								
Date :								
First Named Applicant:	Mr. Sung-Fei Wang							
Confirmation Number:								
Attorney Docket Number:	10233-US-PA							
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<table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Dr. Belinda Lee Registered Number: 46,863</td><td>/Belinda Lee/</td><td>Agent</td></tr></table>			Submitted By:	Elec. Sign.	Sign. Capacity	Dr. Belinda Lee Registered Number: 46,863	/Belinda Lee/	Agent
Submitted By:	Elec. Sign.	Sign. Capacity						
Dr. Belinda Lee Registered Number: 46,863	/Belinda Lee/	Agent						

Documents being submitted:	Files
us-request	10233-usrequ.xml us-request.dtd us-request.xsl
us-assignment	10233-usassn.xml us-assignment.xsl us-assignment.dtd 10233assignment2.tif 10233assignment1.tif
us-fee-sheet	10233-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
application-body	10233-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd 10233US0001.tif 10233US0002.tif 10233US0003.tif
us-declaration	10233declaration1.tif
us-declaration	10233declaration2.tif
Comments Please be kindly advised that the indicated fees of this EFS application is intended to be paid by credit card. However, in the event that the payment through credit card is unsuccessful, the Commissioner is authorized to charge the required fees in connection with this application to: Deposit Account No. 50-2620 (Order No. 10233-US-PA), Deposit Account Name: Jianq Chyun Intellectual Property Office, Authorized User Name: Belinda Lee, E-mail: belinda@jcipgroup.com.tw; usa@jcipgroup.com.tw	